

IN THE SPECIFICATION:

Please insert the following new paragraph after the Title and before the "Technical Field":

-- Related Applications

This application is the U.S. National Phase under 35 U.S.C. § 371 of International Application No. PCT/JP2006/301113, filed on January 25, 2006, which in turn claims the benefit of Japanese Application No. 2005-017423 filed on January 25, 2005, and Japanese Application No. 2005-085440 filed on March 24, 2005 the disclosures of which Applications are incorporated by reference herein. –

Please amend the paragraph beginning on page 24 at line 13 as follows:

[0051] Each circuit board 17 located on the rear of the chassis [[17]] 12 comprises plural electronic components forming the control circuit integrated with the circuit board 17 for performing the light radiation control on a pixel to pixel basis.

Please amend the paragraph beginning on page 30 at line 8 as follows:

The silicone rubber 72 thus positioned allows heat generated from the power transistor [[61]] 16a to be transferred therethrough to the graphite sheet 140 highly efficiently, thereby making it possible to inhibit the temperature of the power transistor 16a from being elevated. Likewise, the electronic component 16d and the graphite sheet 140 are interconnected via silicone rubber 73, thereby making it possible to inhibit the temperature of the electronic component 16d from being elevated.

Please amend the paragraph beginning on page 31 at line 13 as follows:

Likewise, the electronic component 16d is also held between the metal leaf 81 and the metal radiator plate 82. The metal radiator plate 82 and the graphite sheet 140 are interconnected via silicone rubber [[73]] 83. Thus, an elevation in the temperature of the electronic component 16d can be inhibited.

Please amend the paragraph beginning on page 55 at line 24 and bridging page 26 as follows:

As can be understood from the comparison between the results shown in respective of FIGs. 10 and 13, when the back cover 18 is vertically equally divided into the upper half and the lower half, the uneven distribution of the rod-shaped heat transfer members 20 in which the eight rod-shaped heat transfer members 20 are disposed only in the lower half of the back cover 18 in a one-sided fashion as shown in FIG. 9 (FIG. 10) lowered the maximum surface temperature of the back cover 18 as compared with the even distribution of the rod-shaped heat transfer members 20 in which the rod-shaped heat transfer members 20 are evenly distributed throughout the upper and lower halves of the back cover 18 as shown in FIG. 12 (FIG. 13). Specifically, the maximum temperature of the surface temperature contour lines of the back cover 18 of the analytical model 130 (FIG. 9) was higher than room temperature (20°C) by 18°C, while the maximum temperature of the surface temperature contour lines of the back cover 18 of the analytical model ~~130 (FIG. 9)~~ 160 (FIG. 12) was higher than room temperature (20°C) by 22°C.